

# **PROCESS CHAMBER, SEMICONDUCTOR PROCESSING APPARATUS, AND THIN FILM DEPOSITION METHOD**

## **ABSTRACT**

A process chamber, a semiconductor processing apparatus, and a thin film deposition method are provided. This process chamber comprises a reaction chamber, a heating chamber, and a transmission device. A base for supporting a wafer is provided in the reaction chamber. The heating chamber is in communication with the reaction chamber, and a thermal radiation device is provided at a top of the heating chamber and is used for radiating heat toward an interior of the heating chamber. The transmission device is provided in the reaction chamber and is used for supporting the wafer and transmitting the wafer between the reaction chamber and the heating chamber. The presently disclosed process chamber, semiconductor processing apparatus, and thin film deposition method can improve heating efficiency and heating uniformity of the wafer.

Fig. 1